

Flexbase™ G1860 Halogen-Free Copper Polyimide Laminates Modified Epoxy Adhesive

Description

Sheldahl Flexbase G1860 products use our proprietary halogen-free high temperature modified epoxy adhesive to bond polyimide film and copper foil, creating a single or double sided composite. G1860 laminates are engineered for use in flex circuitry applications where soldering and temperature resistance are key.

Features

- **Dielectric:** High stability PI films.
- **Adhesive:** Halogen-free modified polyester epoxy.
- **Available Coppers:** Rolled-Annealed (RA), Electro-Deposited High-Ductility (EDHD) or As-Rolled Untreated (ARNT). EDHD foils are suited for general use and flex to install applications. RA foils are suitable for dynamic flexing applications. ARNT foils are valuable for high frequency applications that require a smooth copper surface on both sides.
- **Stability:** Sheldahl's superior manufacturing process ensures consistent dimensional stability.
- **Processing:** High quality flexible circuits can be produced using standard manufacturing procedures.

Storage

Material stored in original packaging, at temperatures of 40-80°F (4-26°C), and below 70% RH will retain their properties for a minimum of 1 year. Excessive exposure to heat and moisture may cause copper oxidation.

Quality

Sheldahl products are manufactured using quality systems that conform to ISO, QS, and TS quality standards. Key product characteristics are tested and monitored in accordance to IPC standards. Certifications are available with product shipments.

Constructions

- **Film Thickness:** 1, 2, or 5 mils (25, 50, 125 µm)
- **Copper Thickness:** ½, 1, 2 oz/FT² (17, 35, 70 µm)
- **Adhesive Thickness:** Standard thickness is 0.7mil (18µm)
- **Width:** Standard roll width is 24" (610mm)

Specialty thickness and widths available please contact your Sheldahl representative.

Contact Information:

USA: Telephone – 507-663-8344
Europe: Telephone – 33-387-847-477
Worldwide: Telephone – 507-663-8344

Come visit us at www.Sheldahl.com

Ordering Information:

When ordering please specify:

- Film thickness
- Adhesive type (flame-retardant or non flame-retardant)
- Adhesive thickness
- Copper type (ED or RA)
- Copper on one side or both
- Roll width

PROPERTY TO BE TESTED AND TEST METHOD	IPC Test Requirements	Sheldahl Typical Mean Value*
Dimensional Stability, maximum, percentage, IPC-TM-650, 2.2.4 Method B Method C	0.15 0.20	0.06 0.10
Peel Strength, minimum, lb./in. - width, IPC-TM-650, 2.4.9 Method A as received Method B as received Method D After Solder Float Method F after temperature cycling	8.0 8.0 7.0 8.0	9.0 12.0 10.0 12.0
Low Temperature Flexibility, 5 Cycles, IPC-TM-650, 2.6.18	Pass	Pass
Chemical Resistance percentage, IPC-TM-650, 2.3.2, A	80%	90%
Solder Float, IPC-TM-650, 2.4.13, Method B	Pass	Pass
Solderability, J-STD-003, Test A	Pass	Pass
Dielectric constant, maximum (at 1MHz), IPC-TM-650, 2.5.5.3	4.0	3.5
Dissipation factor, maximum (at 1 MHz), IPC-TM-650, 2.5.3	0.040	0.015
Volume Resistivity, minimum megohm-cm, IPC-TM-650, 2.5.17	10^6	10^7
Surface resistance minimum, megohms, IPC-TM-650, 2.5.17	10^5	10^5
Dielectric strength, minimum volts/mil, ASTM-D-149	2000	3500
Fungus Resistance, IPC-TM-650, 2.6.1	Non-Nutrient	Non-Nutrient
Moisture Absorption, maximum, percent, IPC-TM-650, 2.6.2	4.0	2.0
Moisture and Insulation Resistance, minimum, megohms, IPC-TM-650, 2.6.3.2	10^3	10^4

*The information contained herein is based upon typical data, Sheldahl makes no warranties expressed or implied as to its accuracy and assumes no liability arising out of its use by others. The user should determine suitability of Sheldahl materials for each individual application.